

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
Name	Execution Date
ADC Tech International Ltd.	09/16/2010
<b>RECEIVING PARTY DATA</b>	
Name:	Yen Technologies, LLC
Street Address:	2711 Centerville Road
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<b>PROPERTY NUMBERS Total: 1</b>	
Property Type	Number
Patent Number:	6775124
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ATTORNEY DOCKET NUMBER:	088245-6833
NAME OF SUBMITTER:	Paul S. Hunter

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Total Attachments: 4  
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**PATENT**  
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**EXHIBIT B**

**ASSIGNMENT OF PATENT RIGHTS**

For good and valuable consideration, the receipt of which is hereby acknowledged, ADC Tech International Ltd., a Hong Kong limited company having an office at Room 405, 4/F, Winful Centre, 30 Shing Yip Street, Kwun Tong, Kowloon, Hong Kong ("**Assignor**"), does hereby sell, assign, transfer, and convey unto Yen Technologies, LLC, a , having an office at 2711 Centerville Road, Suite 400, Wilmington, Delaware, 19808, U.S.A. ("**Assignee**"), or its designees, all right, title, and interest that exist today and may exist in the future in and to all of the following (collectively, the "**Patent Rights**"), including:

(a) the provisional patent applications, patent applications and patents listed in the Attachment hereto ("**Listed Patents**"),

(b) all patents or patent applications (i) to which any of the foregoing directly or indirectly claim priority, and (ii) for which any of the foregoing directly or indirectly forms a basis for priority, and/or (iii) that were co-owned patent applications that incorporate by reference, or are incorporated by reference into, any of the foregoing, and (iv) that are reissues, reexaminations, extensions, continuations, continuations in part, continuing prosecution applications, or divisions of any of the foregoing, and/or (v) that are foreign patents, patent applications and counterparts to any of the foregoing, including certificates of invention, utility models, industrial design protection, design patent protection, and other governmental grants or issuances and (vi) any of the foregoing in (i)-(iv) whether or not expressly listed as Listed Patents below and whether or not abandoned, rejected, or the like;

(c) inventions, invention disclosures, and discoveries described in any of the Listed Patents and /or any of the foregoing category (b) to the extent that any such inventions, invention disclosures, and discoveries (i) are included in any claim in the Listed Patents and /or any of the foregoing category (b), (ii) are subject matter capable of being reduced to a patent claim in any reissue or reexamination proceedings brought on any of the Listed Patents and /or any of the foregoing category (b), and/or (iii) could have been and/or could be included as a claim in any continuations, continuations in part, continuing prosecution applications, requests for continuing examinations and/or divisions of the Listed Patents and /or any of the foregoing category (b);

(d) rights to apply in any or all countries of the world for patents, certificates of invention, utility models, industrial design protections, design patent protections or other governmental grants or issuances of any type related to the any of the foregoing categories (a), (b) and/or (c), including, without limitation, under the Paris Convention for the Protection of Industrial Property, the International Patent Cooperation Treaty, or any other convention, treaty, agreement or understanding;

(e) causes of action (whether currently pending, filed, or otherwise) and other enforcement rights, including, without limitation, all rights under the Listed Patents and/or under or on account of any of the foregoing categories (b), (c) and/or (d) to

- (i) damages,
- (ii) injunctive relief and
- (iii) other remedies of any kind

for past, current and future infringement; and

(f) all rights to collect royalties and other payments under or on account of any of the Listed Patents or any of the foregoing categories (b) through (e).

Assignor represents, warrants and covenants that:

(1) Assignor has the full power and authority, and has obtained all third party consents, approvals and/or other authorizations required to enter into this Assignment of Patent Rights and to carry out its obligations hereunder, including the assignment of the Patent Rights to Assignee; and

(2) Assignor owns all right, title, and interest to the Patent Rights, including, without limitation, all right, title, and interest to sue for infringement of the Patent Rights. Assignor has obtained and properly recorded previously executed assignments for the Patent Rights as necessary to fully perfect its rights and title therein in accordance with governing law and regulations in each respective jurisdiction. The Patent Rights are free and clear of all liens, claims, mortgages, security interests or other encumbrances, and restrictions. There are no actions, suits, investigations, claims or proceedings threatened, pending or in progress relating in any way to the Patent Rights. There are no existing contracts, agreements, options, commitments, proposals, bids, offers, or rights with, to, or in any person to acquire any of the Patent Rights.

Assignor hereby authorizes the respective patent office or governmental agency in each jurisdiction to issue any and all patents, certificates of invention, utility models or other governmental grants or issuances that may be granted upon any of the Patent Rights in the name of Assignee, as the assignee to the entire interest therein.

The terms and conditions of this Assignment of Patent Rights will inure to the benefit of Assignee, its successors, assigns, and other legal representatives and will be binding upon Assignor, its successors, assigns, and other legal representatives.

[Signature Page to Follow]

IN WITNESS WHEREOF this Assignment of Patent Rights is executed at HK on this 16 day of Sept., 2010.

ASSIGNOR

ADC Tech International Ltd.

By: Gloria Shea

Name: Shea Oi Kan

Title: Director  
(Signature *MUST* be attested)

**ATTESTATION OF SIGNATURE PURSUANT TO 28 U.S.C. §1746**

The undersigned witnessed the signature of Shea Oi Kan to the above Assignment of Patent Rights on behalf of ADC Tech International Ltd. and makes the following statements:

1. I am over the age of 18 and competent to testify as to the facts in this Attestation block if called upon to do so.
2. Shea Oi Kan is personally known to me (or proved to me on the basis of satisfactory evidence) and appeared before me on Sept. 16, 2010 to execute the above Assignment of Patent Rights on behalf of ADC Tech International Ltd..
3. Shea Oi Kan subscribed to the above Assignment of Patent Rights on behalf of ADC Tech International Ltd..

I declare under penalty of perjury under the laws of the United States of America that the statements made in the three (3) numbered paragraphs immediately above are true and correct.

EXECUTED on Sept. 16, 2010 (date)

By: Dina Sli

Print Name: SHEH SHIUT KUN

Attachment  
Listed Patents

Patent No./ Appl. No.	Country	Title	Inventors	Appl. Date
09/887,385	US	Micro-gap gas filled dielectric capacitor	Cheung, William S.H.	11/14/2001
6,775,124	US	Micro-gap gas filled dielectric capacitor	Cheung, William S.H.	11/21/2002
2005/020027005144	WO	A micro-gap gas filled dielectric capacitor	Cheung, William S.H.	11/14/2002
7,387,928	US	Device and method for making air, gas or vacuum capacitors and other microwave components	Cheung, William S. H.	6/6/2006
12/029,702	US	Multi-layer capacitor and method of manufacturing same	Cheung, William S.	2/12/2008
12/692,122	US	Multi-layer capacitor and method of manufacturing same	Cheung, William S.	1/22/2010